Facile preparation of B₄C/C composite aerogel with high specific surface area and low thermal conductivity

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Abstract

Due to the combination of covalent bonds, boron carbide has high hardness, high compressive strength and high oxidation resistance properties ^[1, 2]. Aerogels are threedimensional network structure of nanoporous materials with low density, high porosity, low thermal conductivity and high specific surface area, which make aerogels have excellent thermal insulation properties. Based on the research of SiC aerogel ^[3, 4], we have combined boron carbide with aerogel to synthesis boron carbide-based aerogel. A novel boron carbide-based aerogel with high-temperature resistant and high-strength have been developed through sol-gel route and carbothermal reduction process. The B₄C/C composite aerogels are obtained from low-cost inorganic salt of boron and resorcinol-formaldehyde (RF) as raw materials. The effects of reactant molar ratios and heat treatment time on physicochemical properties of B₄C/C composite aerogels are investigated. The results show that the compressive strength of B₄C/C composite aerogel is as high as 4.25 MPa. The specific surface area of sample is as high as 601.02 m^2/g , which is beneficial for its application of thermal insulation at elevated temperatures. After heat-treated at 1650 °C for 5 h, the thermal conductivity of carbon fiber mat reinforced composite aerogel is as low as $0.051 \text{ W/m} \cdot \text{K}(25 \text{ }^\circ\text{C})$.

Keywords

Aerogel; Boron carbide; Silicon carbide; Compressive strength; Thermal conductivity

Reference

[1] Watts J L, Talbot P C, Alarco J A, et al. Morphology control in high yield boron carbide[J]. Ceramics International, 2016, 43(2): 2650-2657.

[2] Domnich V, Reynaud S, Haber R A, et al. Boron Carbide: Structure, Properties, and Stability under Stress[J]. Journal of the American Ceramic Society, 2011, 94(11):3605-3628.

[3] Zera E, Campostrini R, Aravind P R, et al. Novel SiC/C aerogels through pyrolysis of polycarbosilane precursors[J]. Advanced Engineering Materials. 2014, 16(6): 814-819.

[4] Kong Y, Zhong Y, Shen X, et al. Synthesis of monolithic mesoporous silicon carbide

from resorcinol-formaldehyde/silica composites[J]. Materials Letters. 2013, 99(20): 108-110

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